

### PolyMide™ CoPA

PolyMide™ CoPA is based on a copolymer of Nylon 6 and Nylon 6,6. The filament combines excellent strength, toughness, and heat resistance of up to 180°C.

**Physical Properties** 

Property	Testing method	Typical value
Density	ASTM D792 (ISO 1183, GB/T 1033)	1.12 (g/cm3 at 21.5°C)
Glass transition temperature	DSC, 10 °C/min	67 (°C)
Vicat Softening temperature	ASTM D1525 (ISO 306 GB/T 1633)	180 (°C)
Melt index	260 °C, 1.2 kg	12 (g/10 min)
Melting temperature	DSC, 10 °C/min	190 (°C)
Crystallization temperature	DSC, 10 °C/min	128 (°C)
Decomposition temperature	TGA, 20 °C/min	370 (°C)

Tested with 3D printed specimen of 100% infill

Mechanical Properties (Dry State)

Property	Testing method	Typical value
Young's modulus (X-Y)	ASTM D638 (ISO 527, GB/T 1040)	2223 ± 199 (MPa)
Tensile strength (X-Y)	ASTM D638 (ISO 527, GB/T 1040)	66.2 ± 0.9 (MPa)
Elongation at break (X-Y)	ASTM D638 (ISO 527, GB/T 1040)	9.9 ± 1.5 (%)
Bending modulus (X-Y)	ASTMD790 (ISO 178, GB/T 9341)	1667 ± 118 (MPa)
Bending strength (X-Y)	ASTMD790 (ISO 178, GB/T 9341)	97.0 ± 1.1 (MPa)
Charpy impact strength (X-Y)	ASTM D256 (ISO 179, GB/T 1043)	9.6 ± 1.4 (kJ/m²)

All testing specimens were printed under the following conditions:

nozzle temperature = 265 °C, printing speed = 45 mm/s, build plate temperature = 70 °C, infill = 100%

### Mechanical Properties (Moisture Conditioned)

Property	Testing method	Typical value
Young's modulus (X-Y)	ASTM D638 (ISO 527, GB/T 1040)	1053 ± 235 (MPa)
Tensile strength (X-Y)	ASTM D638 (ISO 527, GB/T 1040)	31.4 ± 1.5 (MPa)
Elongation at break (X-Y)	ASTM D638 (ISO 527, GB/T 1040)	216.5 ± 12.1 (%)
Bending modulus	ASTMD790 (ISO 178, GB/T 9341)	862.8 ± 133.3 (MPa)
Bending strength	ASTMD790 (ISO 178, GB/T 9341)	41.6 ± 11.6 (MPa)
Charpy impact strength	ASTM D256 (ISO 179, GB/T 1043)	17.2 ± 1.4 (kJ/m²)

All specimens were annealed at 80 °C for 30 min, and conditioned at 50% relative humidity and ambient temperature for 15 days prior to testing

All specimens were annealed at 80°C for 30min and dried for 48h prior to testing



#### Nov. 2018

# Technical Data Sheet

Version 4.0

Recommended printing conditions

Parameter	
Nozzle temperature	250 - 270 (°C)
Build Surface material	PA film, PI film
Build surface treatment	Applying PVA glue to the build surface
Build plate temperature	25 - 70 (°C)
Cooling fan	Turned off
Printing speed	30 - 50 (mm/s)
Raft separation distance	0.1 - 0.2 (mm)
Retraction distance	3-6 (mm)
Retraction speed	40 - 60 (mm/s)
Recommended environmental temperature	40 - 60 (°C)
Threshold overhang angle	55 (°)
Recommended support material	PolyDissolve™ S1

Based on 0.4 mm nozzle and Simplify 3D v.3.1. Printing conditions may vary with different nozzle diameters

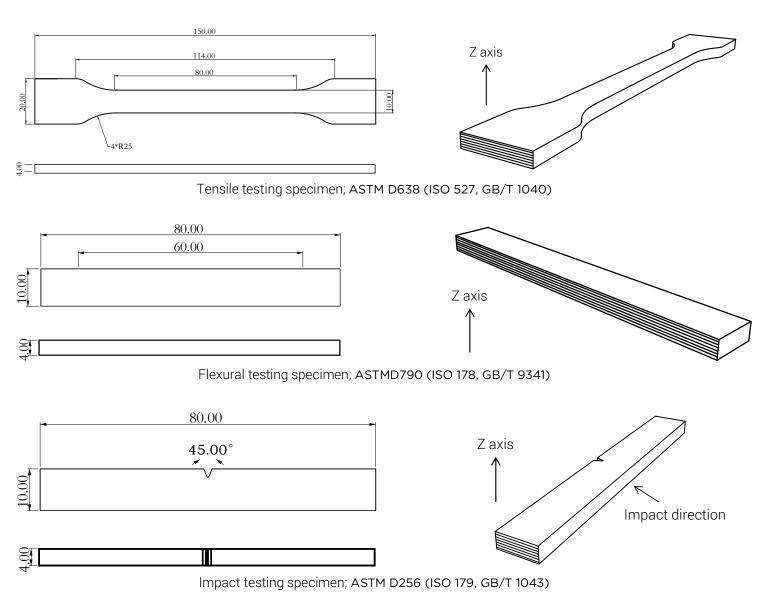
It is highly recommended to use the PolyBox<sup>™</sup> when printing with PolyMide<sup>™</sup> CoPA and to store it in the resealable bag. To ensure a good heat resistance of your printed part it is recommended to anneal your PolyMide<sup>™</sup> CoPA 3d printed model. Annealing settings: 70°C for 2h





## **Technical Data Sheet**

Version 4.0



### Disclaimer:

The typical values presented in this data sheet are intended for reference and comparison purposes only. They should not be used for design specifications or quality control purposes. Actual values may vary significantly with printing conditions. End- use performance of printed parts depends not only on materials, but also on part design, environmental conditions, printing conditions, etc. Product specifications are subject to change without notice.

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